

SEMiX151GB12Vs



SEMiX® 1s

SEMiX151GB12Vs

Features

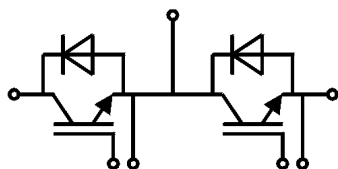
- Homogeneous Si
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperature limited to $T_C=125^\circ\text{C}$ max.
- Product reliability results are valid for $T_j=150^\circ\text{C}$



GB

Absolute Maximum Ratings

Symbol	Conditions	Values	Unit
IGBT			
V_{CES}	$T_j = 25^\circ\text{C}$	1200	V
I_C	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	231
		$T_c = 80^\circ\text{C}$	176
I_{Cnom}		150	A
I_{CRM}	$I_{CRM} = 3 \times I_{Cnom}$	450	A
V_{GES}		-20 ... 20	V
t_{psc}	$V_{CC} = 720\text{ V}$ $V_{GE} \leq 15\text{ V}$ $V_{CES} \leq 1200\text{ V}$	$T_j = 125^\circ\text{C}$	10
T_j		-40 ... 175	$^\circ\text{C}$
Inverse diode			
I_F	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	189
		$T_c = 80^\circ\text{C}$	141
I_{Fnom}		150	A
I_{FRM}	$I_{FRM} = 3 \times I_{Fnom}$	450	A
I_{FSM}	$t_p = 10\text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$	900	A
T_j		-40 ... 175	$^\circ\text{C}$
Module			
$I_{t(RMS)}$	$T_{terminal} = 80^\circ\text{C}$	600	A
T_{stg}		-40 ... 125	$^\circ\text{C}$
V_{isol}	AC sinus 50Hz, $t = 1\text{ min}$	4000	V

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
IGBT					
$V_{CE(sat)}$	$I_C = 150\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel		$T_j = 25^\circ\text{C}$	1.75	2.20
			$T_j = 150^\circ\text{C}$	2.20	2.50
V_{CE0}	chipelevel		$T_j = 25^\circ\text{C}$	0.94	1.04
			$T_j = 150^\circ\text{C}$	0.88	0.98
r_{CE}	$V_{GE} = 15\text{ V}$ chipelevel		$T_j = 25^\circ\text{C}$	5.4	7.7
			$T_j = 150^\circ\text{C}$	8.8	10.1
$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C = 6\text{ mA}$	5.5	6	6.5	V
I_{CES}	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$		$T_j = 25^\circ\text{C}$	0.1	0.3
			$T_j = 150^\circ\text{C}$		
C_{ies}	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$		$f = 1\text{ MHz}$	9.0	nF
C_{oes}			$f = 1\text{ MHz}$	0.89	nF
C_{res}			$f = 1\text{ MHz}$	0.88	nF
Q_G	$V_{GE} = -8\text{ V...} + 15\text{ V}$			1650	nC
R_{Gint}	$T_j = 25^\circ\text{C}$			5.00	Ω
$t_{d(on)}$	$V_{CC} = 600\text{ V}$		$T_j = 150^\circ\text{C}$	319	ns
t_r	$I_C = 150\text{ A}$		$T_j = 150^\circ\text{C}$	46	ns
E_{on}	$V_{GE} = \pm 15\text{ V}$		$T_j = 150^\circ\text{C}$	19.4	mJ
$t_{d(off)}$	$R_{G on} = 1\text{ }\Omega$		$T_j = 150^\circ\text{C}$	482	ns
t_f	$R_{G off} = 1\text{ }\Omega$		$T_j = 150^\circ\text{C}$	68	ns
E_{off}	$di/dt_{on} = 4600\text{ A}/\mu\text{s}$ $di/dt_{off} = 1700\text{ A}/\mu\text{s}$ $du/dt_{off} = 6700\text{ V}/\mu\text{s}$		$T_j = 150^\circ\text{C}$	17.1	mJ
$R_{th(j-c)}$	per IGBT			0.19	K/W

SEMiX151GB12Vs



SEMiX151GB12Vs

Features

- Homogeneous Si
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

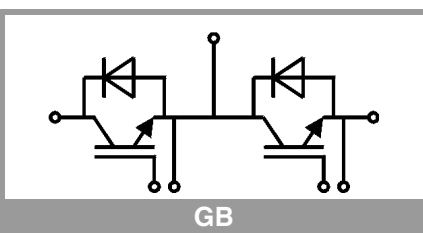
Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperature limited to $T_C=125^\circ\text{C}$ max.
- Product reliability results are valid for $T_J=150^\circ\text{C}$

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
$V_F = V_{EC}$	$I_F = 150\text{ A}$	$T_j = 25\text{ }^{\circ}\text{C}$		2.14	2.46	V
	$V_{GE} = 0\text{ V}$ chiplevel	$T_j = 150\text{ }^{\circ}\text{C}$		2.07	2.38	V
V_{F0}	chiplevel	$T_j = 25\text{ }^{\circ}\text{C}$	1.1	1.3	1.5	V
		$T_j = 150\text{ }^{\circ}\text{C}$	0.7	0.9	1.1	V
r_F	chiplevel	$T_j = 25\text{ }^{\circ}\text{C}$	4.3	5.6	6.4	mΩ
		$T_j = 150\text{ }^{\circ}\text{C}$	7.0	7.8	8.5	mΩ
I_{RRM}	$I_F = 150\text{ A}$	$T_j = 150\text{ }^{\circ}\text{C}$		175		A
Q_{rr}	$di/dt_{off} = 4400\text{ A}/\mu\text{s}$	$T_j = 150\text{ }^{\circ}\text{C}$		27.5		μC
E_{rr}	$V_{GE} = -15\text{ V}$ $V_{CC} = 600\text{ V}$	$T_j = 150\text{ }^{\circ}\text{C}$		11.5		mJ
$R_{th(j-c)}$	per diode				0.31	K/W
Module						
L_{CE}				16		nH
$R_{CC'+EE'}$	res., terminal-chip	$T_C = 25\text{ }^{\circ}\text{C}$		0.7		mΩ
		$T_C = 125\text{ }^{\circ}\text{C}$		1		mΩ
$R_{th(c-s)}$	per module			0.075		K/W
M_s	to heat sink (M5)		3		5	Nm
M_t		to terminals (M6)	2.5		5	Nm
						Nm
w				145		g
Temperatur Sensor						
R_{100}	$T_C=100^{\circ}\text{C}$ ($R_{25}=5\text{ k}\Omega$)			$493 \pm 5\%$		Ω
$B_{100/125}$	$R(T)=R_{100}\text{exp}[B_{100/125}(1/T-1/T_{100})]$; $T[\text{K}]$;			$3550 \pm 2\%$		K



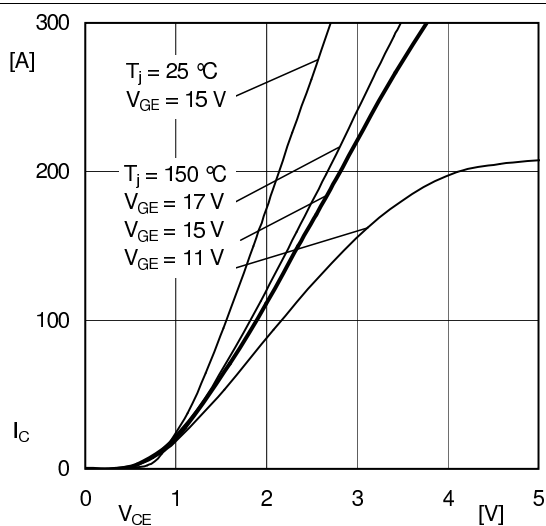


Fig. 1: Typ. output characteristic, inclusive $R_{CC'} + E_{E'}$

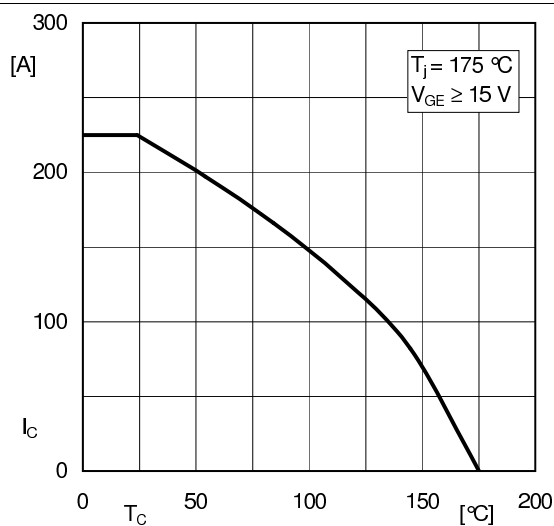


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

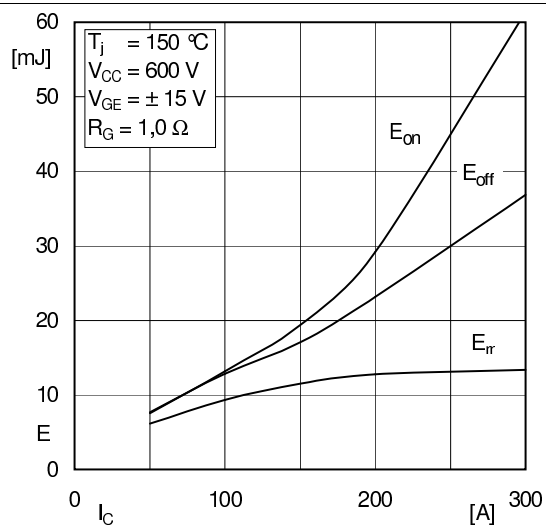


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

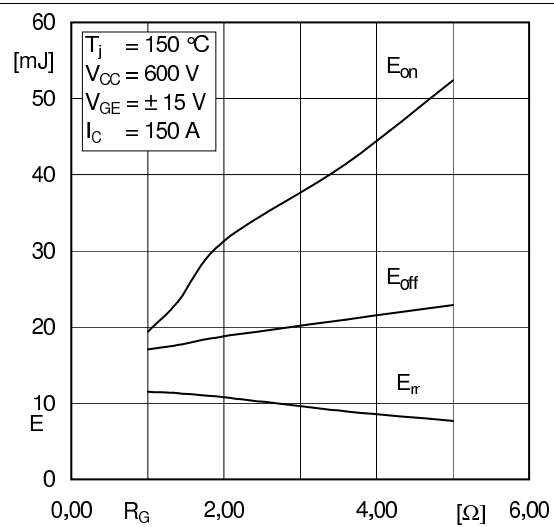


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

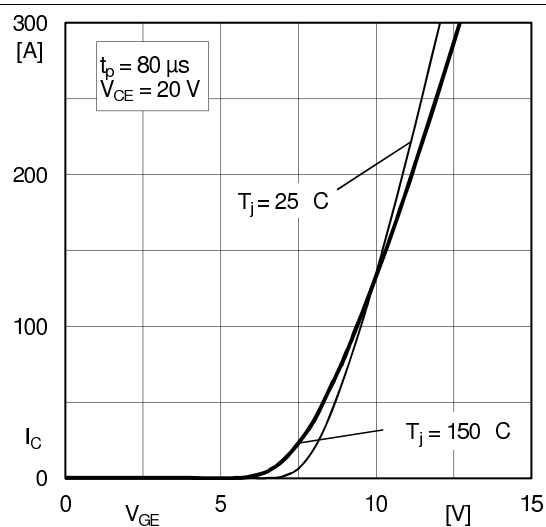


Fig. 5: Typ. transfer characteristic

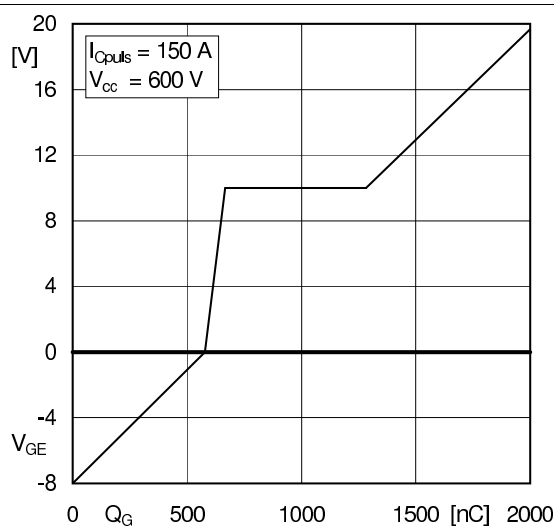


Fig. 6: Typ. gate charge characteristic

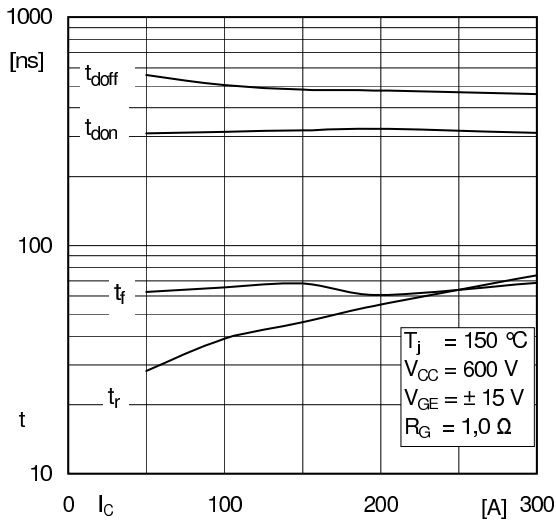


Fig. 7: Typ. switching times vs. I_C

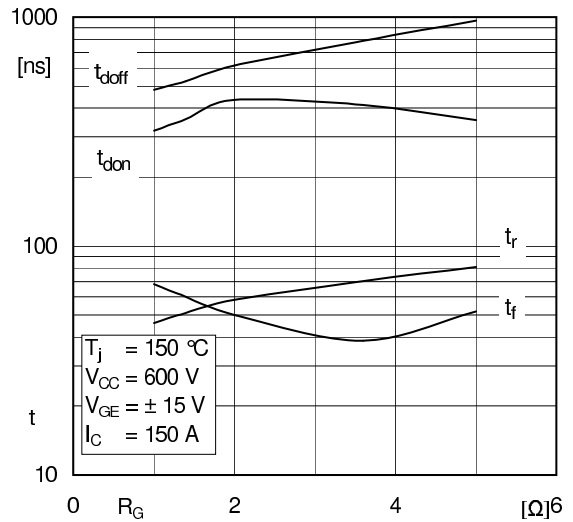


Fig. 8: Typ. switching times vs. gate resistor R_G

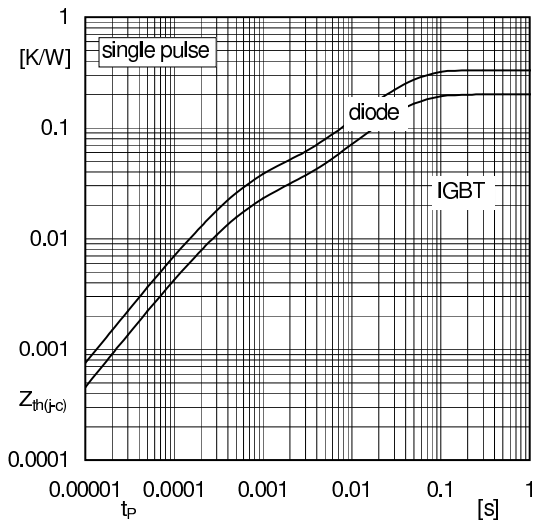


Fig. 9: Typ. transient thermal impedance

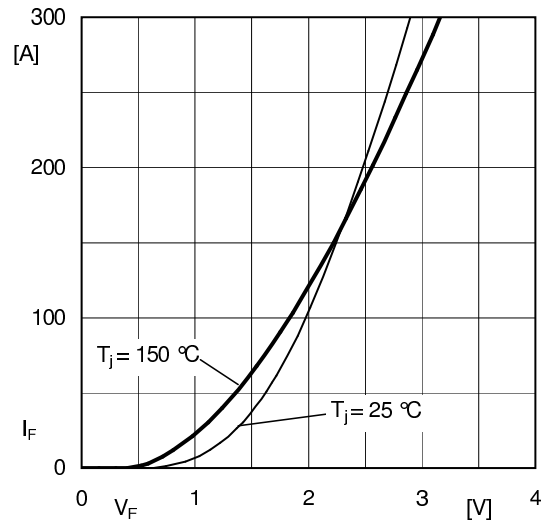


Fig. 10: Typ. CAL diode forward charact., incl. $R_{CC'+EE'}$

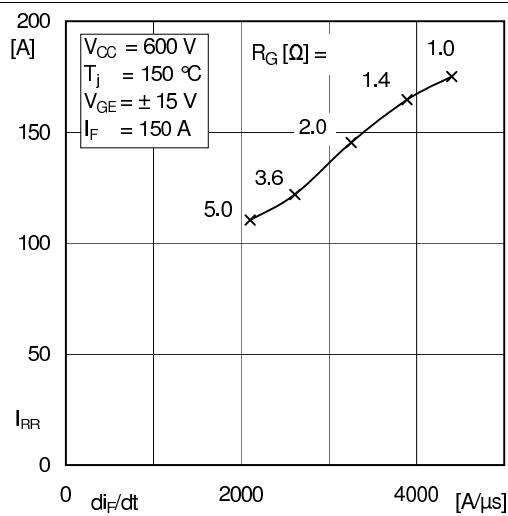


Fig. 11: Typ. CAL diode peak reverse recovery current

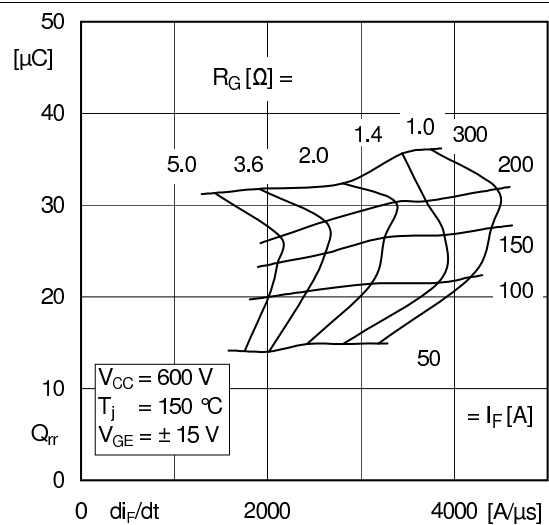
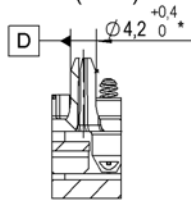


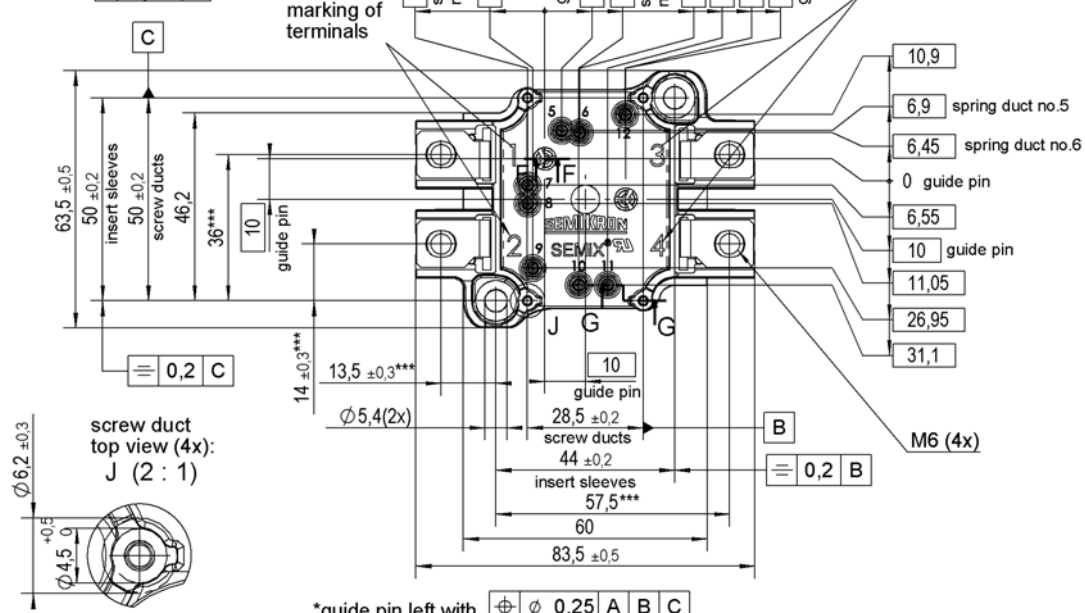
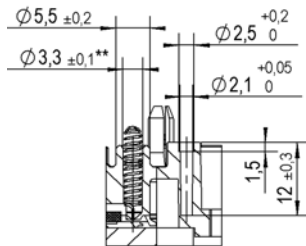
Fig. 12: Typ. CAL diode recovery charge

Case: SEMiX 1s

guide pin left:
F-F (1 : 1)



screw duct (4x)
spring duct (8x):
G-G (1 : 1)



*guide pin left with

	$\varnothing$ 0,25	A	B	C
---	--------------------	---	---	---

**guide pin right / spring ducts with

	$\varnothing$	0,5	A	B	D
---	---------------	-----	---	---	---

***movable M6 nuts (clearance for mounting)

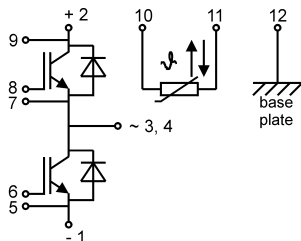
Rules for the contact PCB:

- holes guidepins = $\varnothing 4,0 \pm 0,1$ / position tolerance $\pm 0,1$
- holes for screws = $\varnothing 3,3 \pm 0,1$ / position tolerance $\pm 0,1$
- spring contact pad = $\varnothing 3,6 \pm 0,1$ / position tolerance $\pm 0,1$

general tolerance:
ISO 2768-m
ISO 8015

All measures in Z-direction
valid when mounted to heat sink

SEMiX 1s



spring configuration

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.